

## AMENDMENT

### **Amendment to the Claims**

Please amend claims 1, 22, 23 and 24 as follows:

Claims 1-10 (Canceled)

11. (Currently Amended) A process for the partial demetallization of a first multilayer substrate comprising a coextruded film comprising a polypropylene layer, an adhesive layer and a metallic layer, the process comprising applying an etchant lacquer comprising at least one metal dissolving etchant on the metallic layer in a quantity of about the stoichiometrical amount needed to dissolve the metallic layer and to eliminate any chemical reactivity of the at least one etchant towards the adhesive layer, wherein the dissolved metal remains within the multilayer structure substrate, and the dissolution of the metal creates a substantially transparent window in the metallic layer in a washing-free step.

12. (Previously Presented) The process of claim 11, wherein the process is carried out on standard gravure or flexo printing presses or coating equipment.

13. (Previously Presented) The process of claim 11, further comprising a lamination step of the partly demetallized multilayer substrate with a second substrate.

14. (Previously Presented) The process of claim 11, further comprising a coating operation for treating the first multilayer substrate.

15. (Previously Presented) The process of claim 11, further comprising a printing operation for treating the first multilayer substrate.

16. (Previously Presented) The process of claim 11, further comprising a coating operation and a printing operation for treating the first multilayer substrate.

17. (Previously Presented) The process of claim 14, wherein the coating operation comprising a coating in register with the demetallized area on a surface of the substrate that is different than where the demetallization is carried out.

18. (Previously Presented) The process of claim 15, wherein the printing operation comprises a patterned print in register with the demetallized area on a surface of the substrate that is different than where the demetallization is carried out.

19. (Previously Presented) The process of claim 12, wherein the amount the etchant lacquer is fine-tuned by choosing a suitable gravure cylinder depth.

20. (Previously Presented) The process of claim 11, wherein the amount the etchant lacquer is fine-tuned by adapting the concentration of the at least one etchant.

21. (Previously Presented) The process of claim 12, wherein the amount of the etchant lacquer is fine-tuned by choosing a suitable gravure cylinder depth and by adapting the concentration of the at least one etchant.

22. (Currently Amended) The process of ~~claim 1~~ claim 11, wherein the demetallization step achieves a light transmission of at least 90% within the demetallized area.

23. (Currently Amended) The process of ~~claim 1~~ claim 11, wherein the concentration of the at least one etchant corresponds to a slight excess of the stoichiometrical amount needed to dissolve the amount of metal present on the multilayer substrate.

24. (Currently Amended) A multilayer substrate obtainable by the process of ~~claim 1~~ claim 11, comprising a window in a supported metallic layer wherein the window has the total quantity of a residue resulting from the demetallization by means of the etchant lacquer.